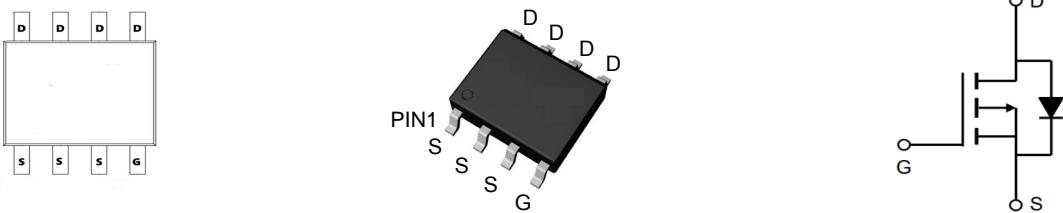


TM15P03S
P-Channel Enhancement Mosfet

General Description <ul style="list-style-type: none"> Low $R_{DS(ON)}$ RoHS and Halogen-Free Compliant Applications <ul style="list-style-type: none"> Load switch PWM 	General Features <p> $V_{DS} = -30V$ $I_D = -15A$ $R_{DS(ON)} = 9.5m\Omega$ (typ.) @ $V_{GS} = -10V$ </p> <p> 100% UIS Tested 100% R_g Tested </p> 
S:SOP-8L  Marking: 4407	

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-15	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-9	A
I_{DM}	Pulsed Drain Current ²	-50	A
EAS	Single Pulse Avalanche Energy ³	55	mJ
I_{AS}	Avalanche Current	-50	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	4.5	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	75	°C/W
	Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	---	40	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	24	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D = -250\mu\text{A}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -30\text{V}$, $V_{GS}=0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}= \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D = -250\mu\text{A}$	-1.0	-1.5	-2.5	V
$R_{DS(\text{on})}$ Note3	Static Drain-Source on-Resistance	$V_{GS} = -10\text{V}$, $I_D = -10\text{A}$	-	9.5	16	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}$, $I_D = -5\text{A}$	-	17	22	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -15\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	1770	-	pF
C_{oss}	Output Capacitance		-	233	-	pF
C_{rss}	Reverse Transfer Capacitance		-	206	-	pF
Q_g	Total Gate Charge	$V_{DS} = -15\text{V}$, $I_D = -5\text{A}$, $V_{GS} = -10\text{V}$	-	22	-	nC
Q_{gs}	Gate-Source Charge		-	1.0	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	1.8	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -15\text{V}$, $I_D = -10\text{A}$, $V_{GS} = -10\text{V}$, $R_{\text{GEN}} = 2.5\Omega$	-	9	-	ns
t_r	Turn-on Rise Time		-	13	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	48	-	ns
t_f	Turn-off Fall Time		-	20	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current		-	-	-15	A
I_{sM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-60	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s = -15\text{A}$	-	-0.8	-1.2	V
trr	Reverse Recovery Time	$T_J=25^\circ\text{C}$, $V_{DD} = -24\text{V}$, $I_F = -2.8\text{A}$, $dI/dt = -100\text{A}/\mu\text{s}$	-	64	-	ns
Qrr	Reverse Recovery Charge		-	25	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

 2. EAS condition: $T_J=25^\circ\text{C}$, $V_{GS}=10\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=-12.7\text{A}$

 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

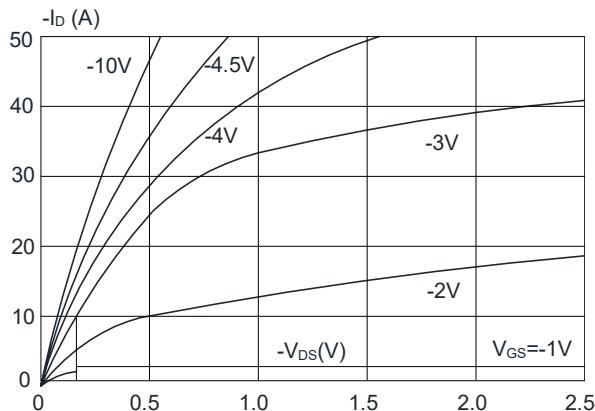


Figure 3: On-resistance vs. Drain Current

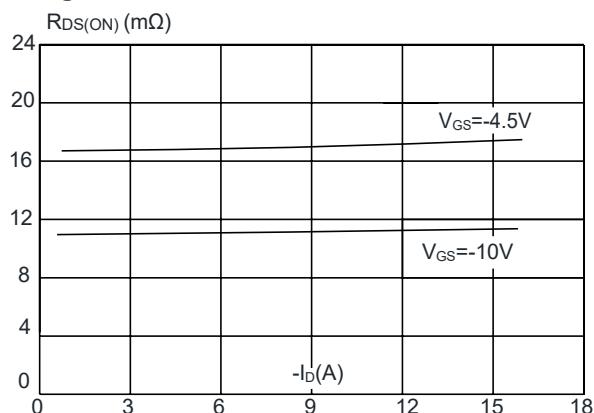


Figure 5: Gate Charge Characteristics

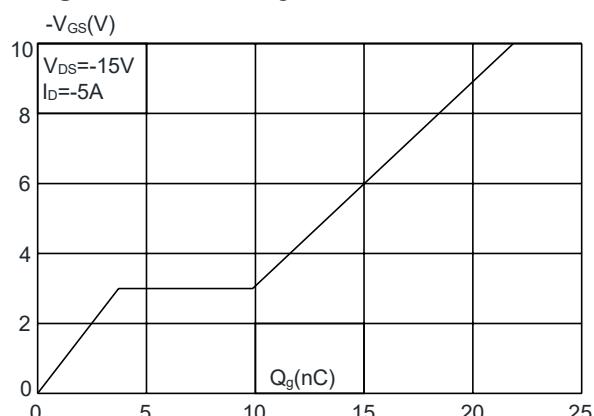


Figure 2: Typical Transfer Characteristics

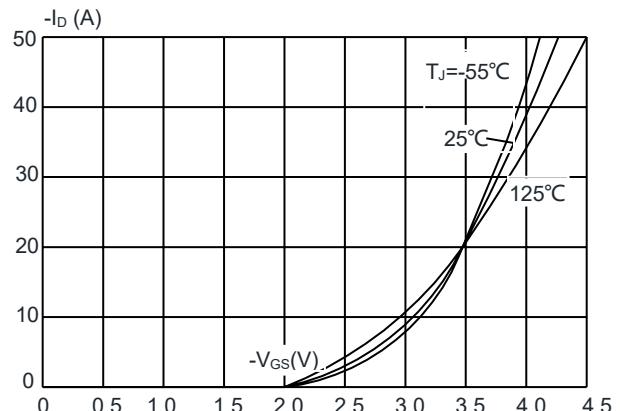


Figure 4: Body Diode Characteristics

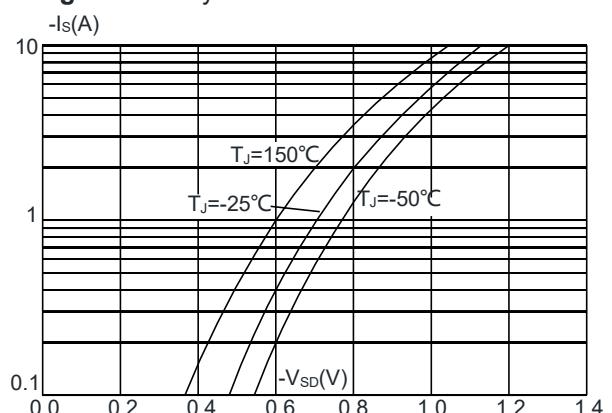
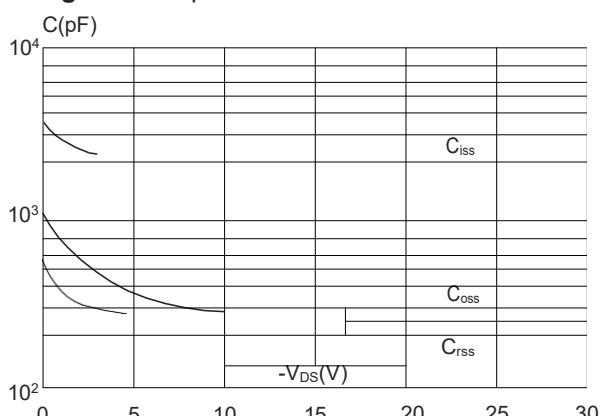


Figure 6: Capacitance Characteristics



TM15P03S

P-Channel Enhancement Mosfet

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

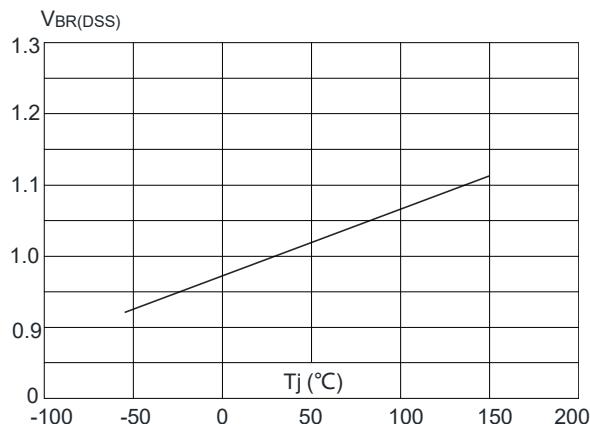


Figure 8: Normalized on Resistance vs. Junction Temperature

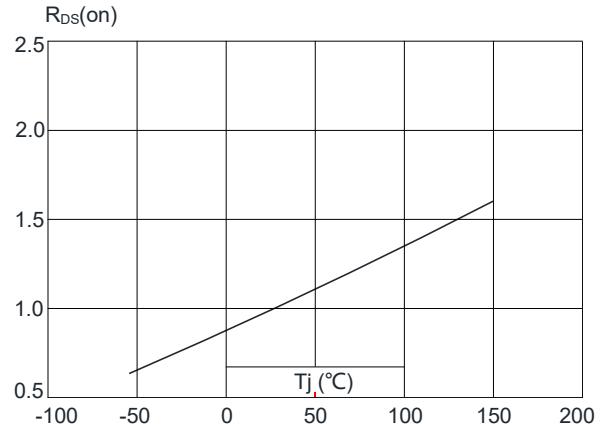


Figure 9: Maximum Safe Operating Area

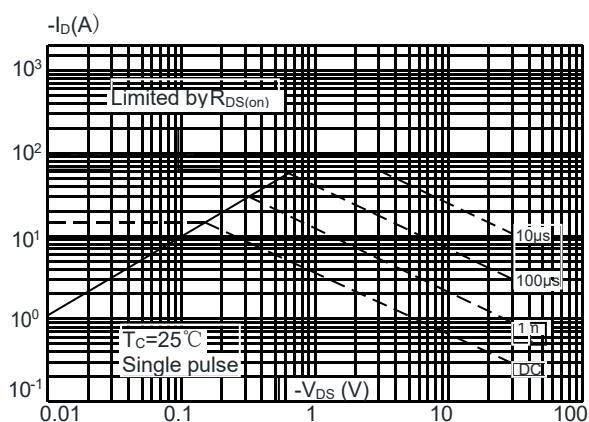


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

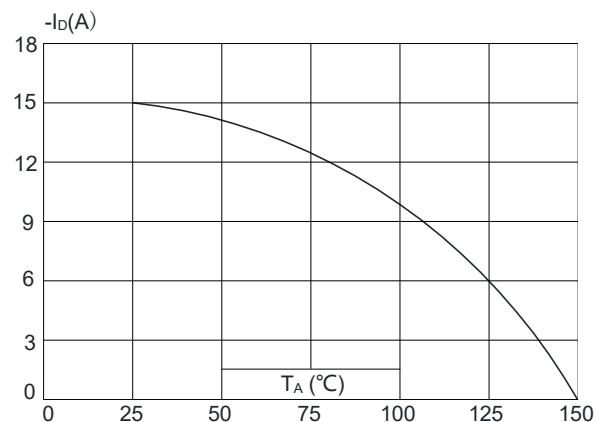
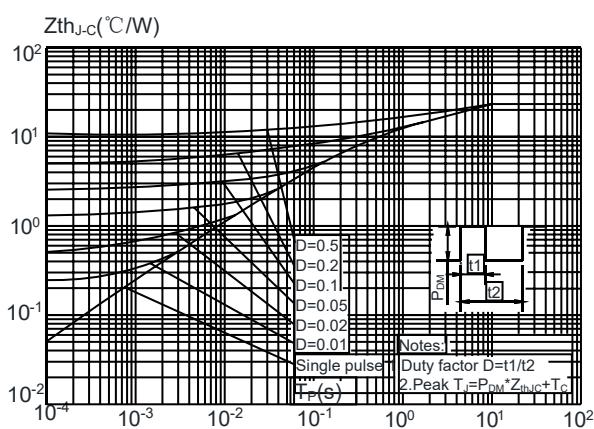
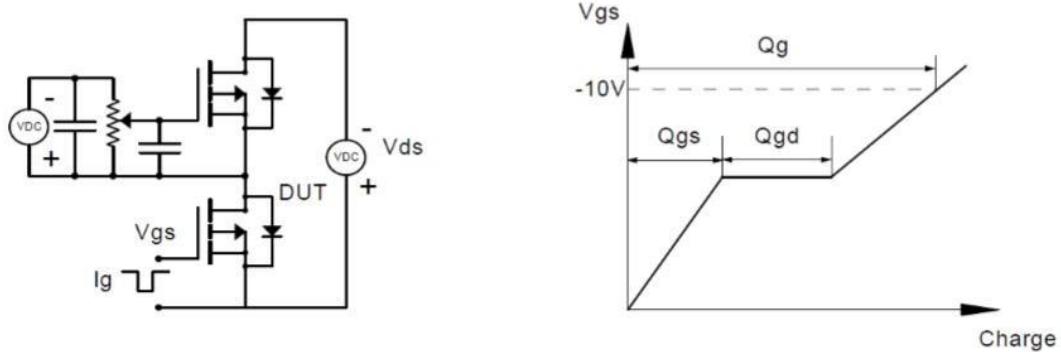


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

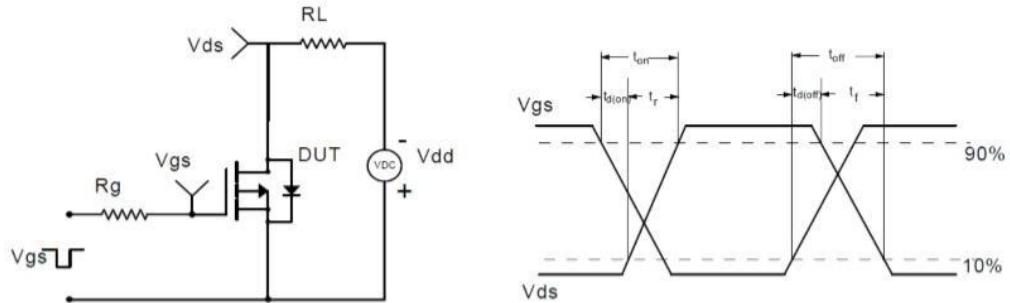


Test Circuit

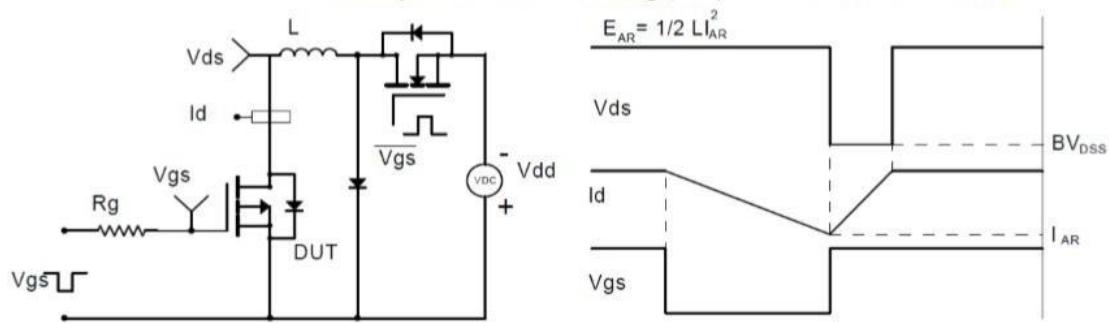
Gate Charge Test Circuit & Waveform



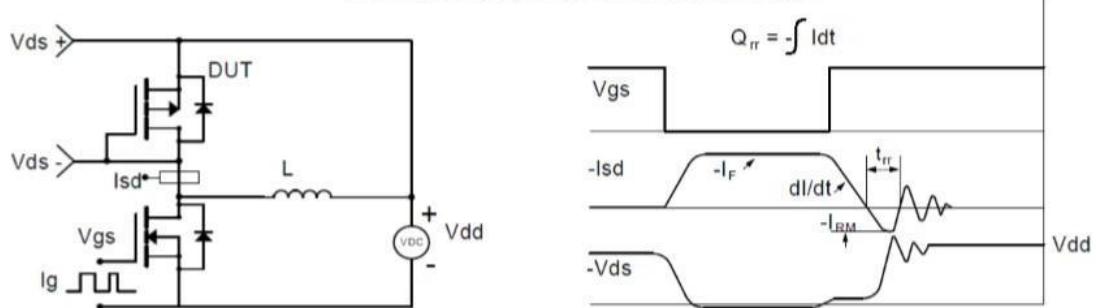
Resistive Switching Test Circuit & Waveforms



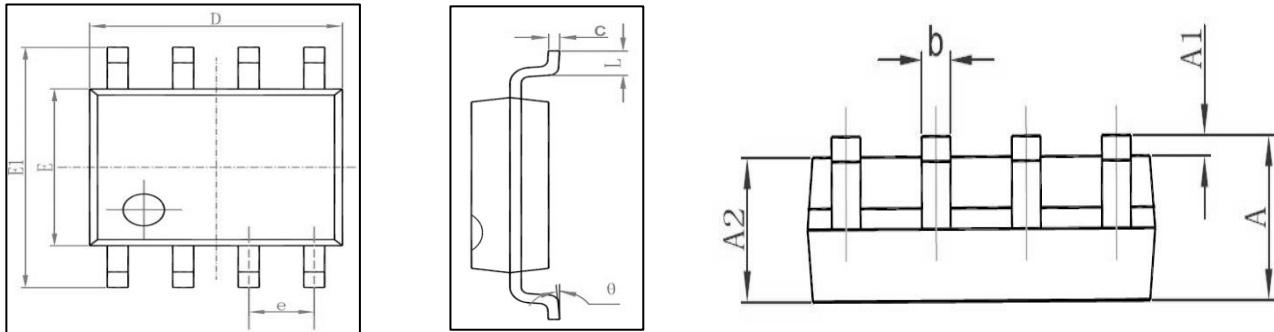
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Mechanical Data:SOP-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

